

Title (en)

CYANIDE-FREE ELECTROPLATING BATH FOR DEPOSITION OF GOLD AND GOLD ALLOYS

Title (de)

CYANIDFREIES GALVANISCHES BAD ZUR ABSCHIEDUNG VON GOLD UND GOLDLEGIERUNGEN

Title (fr)

BAIN GALVANOPLASTIQUE SANS CYANURE POUR DEPOT D'OR ET D'ALLIAGES D'OR

Publication

EP 0907767 A1 19990414 (DE)

Application

EP 97933686 A 19970721

Priority

- DE 19629658 A 19960723
- EP 9703903 W 19970721

Abstract (en)

[origin: DE19629658A1] Cyanide-free electroplating baths for deposition of gold and gold alloy coatings, using sulfurous gold complexes that are stable for a relatively long time, can be used with current densities over 1 A/dm² and are practically odor-free, are obtained when the sulfurous compounds used are mercaptosulfonic acids, disulfide sulfonic acids or salts thereof.

IPC 1-7

C25D 3/48; **C25D 3/62**

IPC 8 full level

C25D 3/48 (2006.01); **C25D 3/62** (2006.01)

CPC (source: EP KR US)

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Citation (search report)

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